

## Application Data Sheet

### Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested classification::	
Suggested Group Art Unit::	
CD-ROM or CD-R?::	None
Computer Readable Form (CRF)?::	No
Title::	WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD
Attorney Docket Number::	025311-0115
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	3
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

### Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japanese
Status::	Full Capacity
Given Name::	Yoshimasa
Family Name::	KAWASE
City of Residence::	Kanagawa
Country of Residence::	Japan

**Street of mailing address::** c/o Semiconductor Leading Edge Technologies, Inc.  
292 Yoshida-cho, Totsuka-ku, Yokohama  
Kanagawa 244-0817, Japan

**Country of mailing address::** Japan

#### Correspondence Information

**Correspondence Customer Number::** 22428

**E-Mail address::** wellis@foleylaw.com

#### Representative Information

<b>Representative Customer Number::</b>	22428	
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#### Domestic Priority Information

<b>Application::</b>	<b>Continuity Type::</b>	<b>Parent Application::</b>	<b>Parent Filing Date::</b>

#### Foreign Priority Information

<b>Country::</b>	<b>Application number::</b>	<b>Filing Date::</b>	<b>Priority Claimed::</b>
Japan	2001-036040	02/13/2001	Yes

#### Assignee Information

**Assignee name::** SEMICONDUCTOR LEADING EDGE  
TECHNOLOGIES, INC.